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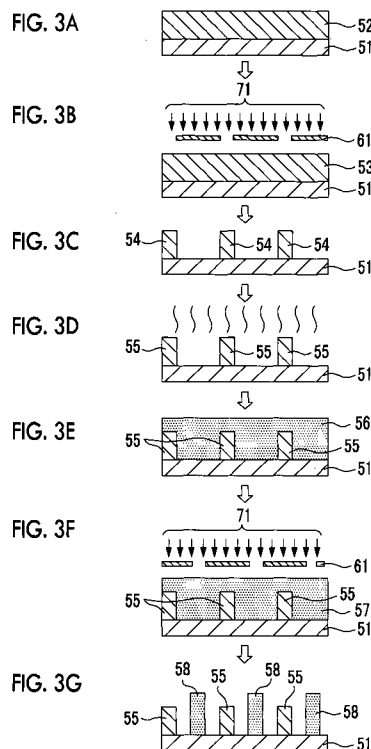
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(54) Title: PATTERN FORMING METHOD, AND, ELECTRONIC DEVICE PRODUCING METHOD AND ELECTRONIC
DEVICE, EACH USING THE SAME



(57) Abstract: A pattern forming method includes: (a) forming a first film on a sub-
strate using an actinic ray-sensitive or radiation-sensitive resin composition (I) con-
taining a resin of which solubility in a developer containing an organic solvent de-
creases due to polarity increased by an action of an acid; (b) exposing the first film;
(c) developing the exposed first film using a developer containing an organic
solvent to form a first negative pattern; (e) forming a second film on the substrate
using an actinic ray-sensitive or radiation-sensitive resin composition (II) containing
a resin of which solubility in a developer containing an organic solvent decreases
due to polarity increased by an action of an acid; (f) exposing the second film; and
(g) developing the exposed second film using a developer containing an organic
solvent to form a second negative pattern in this order.



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